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PATENT NUMBER and ISSUE DATE

## U.S. UTILITY Patent Application

APPL NUM 10031000	FILING DATE 01/16/2002	CLASS 438	SUBCLASS	GAU 2812	EXAMINER	_
**APPLICANT	-		to: Akiguchi T		⁄liyakawa Hidenori;	<u>r</u>
**CONTINUING	G DATA VERIFIED	):			nyakawa Hisenori;	
** FOREIGN APPLICATIONS VERIFIED:						
JAPAN 11/202547 07/16/1988 S JAPAN 2000-63686 03/08/2000 S						
PG-PUB DO N	OT PUBLISH 🗖		RESCIN	p 🗆		j
Foreign priority clair		□ yes	i⊒ no		ATTORNEY DOCKET NO	}
35 USC 119 condition Verified and Acknow	ons met vledged Examiners's int	□ yes ials	□ no		2002-0024A	
TITLE: Package of semiconductor device and method of manufacture thereof						
U.S.DEPT OF COMM./PAT & TM-PTO-435L(Rev 12-54)						

NOTICE OF ALLOWANCE MAILED			CLAIMS ALLOWED					
		Assistant Examiner	Total Claims		Print Claim for O.G			
ISSUE FEE			DRAWING					
Amount Due	Date Paid	7	Sheets Drwg.	Figs.Drwg.	Print Fig.			
		Primary Examiner			<u> </u>			
TERMINAL		PREPARED FOR ISSUE	Application Examiner					
	DISCLAMER	WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.						

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